

# INTERNATIONAL STANDARD

# IEC 61076-4-108

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## Connectors for electronic equipment –

### Part 4-108:

**Printed board connectors with assessed quality –  
Detail specification for cable-to-board connectors,  
with a modular pitch of 25 mm and integrated  
shielding function, applicable for transverse  
packing density of 15 mm, having a basic grid  
of 2,5 mm in accordance with IEC 60917-1**

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## Annex A (informative) Shielding effectiveness

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**CONNECTORS FOR ELECTRONIC EQUIPMENT –****Part 4-108: Printed board connectors with assessed quality –  
Detail specification for cable-to-board connectors, with a modular pitch  
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International Standard IEC 61076-4-108 has been prepared by subcommittee 48B: Connectors, of IEC technical committee 48: Electromechanical components and mechanical structures for electronic equipment.

The text of this standard is based on the following documents:

FDIS	Report on voting
48B/1122/FDIS	48B/1170/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated when a new edition is prepared.

The QC number that appears on the front cover of this publication is the specification number in the IEC Quality Assessment System for Electronic Components (IECQ).

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

Annex A is for information only.

The committee has decided that the contents of this publication will remain unchanged until 2004. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.